

Product / Process Change Notification



N° 2013-170-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an alternative wafer production site for products with Infineon® SFET2 base chip and SSMART top chip technology and introduction of an alternative wafer test site for
BTS50070-1TMA
BTS50080-1TMA
BTS50080-1TMB
BTS50080-1TMC

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **21. February 2014**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46-C", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response within the given time limit we consider this as the acceptance of the PCN.

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SUBJECT OF CHANGE: Introduction of an alternative wafer production site in Kulim for HIC-PROFET™ with base chip SFET2 and top chip SSMART technology and introduction of an alternative wafer test site in Kulim.

PRODUCTS AFFECTED:	Device	SP N°	OPN	Package
	BTS50070-1TMA	SP000411772	BTS500701TMAATMA1	PG-TO220-7-4
	BTS50080-1TMA	SP000385909	BTS500801TMAATMA1	PG-TO220-7-4
	BTS50080-1TMB	SP000385910	BTS500801TMTAKSA1	PG-TO220-7-12
	BTS50080-1TMC	SP000479402	BTS500801TMCATMA1	PG-TO220-7-4

REASON OF CHANGE: Expansion of wafer production capacity for HIC PROFET™ with base chip SFET2 and top chip SSMART technology.

Due to continuously raising demand for Infineon automotive products we have to implement the well-known FE location Kulim as additional wafer production site and test location

We also secure the supply chain with a second front end wafer production site.

DESCRIPTION OF CHANGE:	<u>Current</u>	<u>NEW (additional)</u>
Base chip SFET2		
Wafer production site	Infineon Technologies AG Villach, Austria or Infineon Technologies AG Regensburg, Germany	Infineon Technologies AG Kulim, Malaysia
Wafer test site	Infineon Technologies AG Villach, Austria or Infineon Technologies AG Regensburg, Germany	Infineon Technologies AG Kulim, Malaysia
Top chip SSMART		
Wafer production site	Infineon Technologies AG Villach, Austria	Infineon Technologies AG Kulim, Malaysia
Wafer test site	Infineon Technologies AG Villach, Austria	Infineon Technologies AG Kulim, Malaysia

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PRODUCT IDENTIFICATION:

Base chip SFET2: Wafer lot numbers from Regensburg start with RUxxxxxx, from Villach with VExxxxxx and from Kulim start with 1Exxxxxx.
Top chip SSMART: Wafer lot numbers from Villach start with VExxxxxx and from Kulim with 1Exxxxxx
Traceability assured via date code.
No change in SP ordering number

TIME SCHEDULE:

■ Final qualification report:	available
■ First samples available:	available
■ Start of delivery:	July 2014 onwards or earlier after customer release
■ Last order date of unchanged product:	July 2014
■ Last delivery date of unchanged product:	January 2015

ASSESSMENT:

No impact on electrical performance. Quality and reliability verified by qualification.
There is no change in form, fit and function.

DOCUMENTATION:

2_cip13170 qualification report
3_cip13170 customer info package SSMART
4_cip13170 customer info package SFET2
5_cip13170 AMSA studies